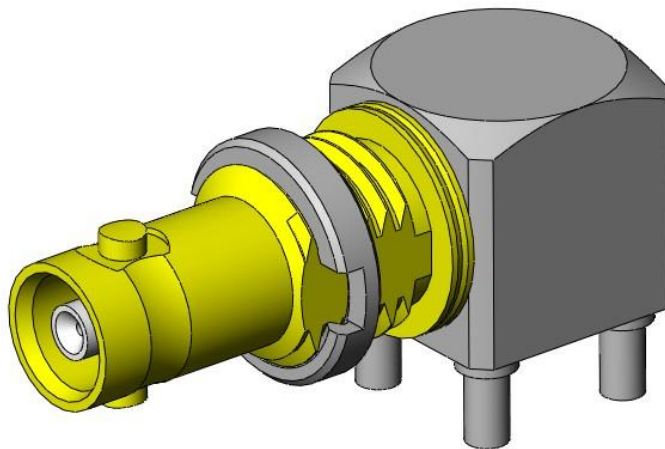
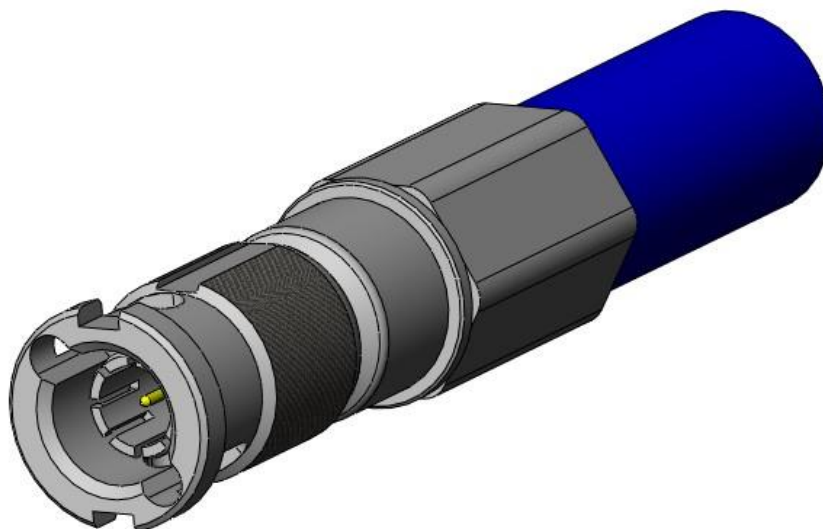


Series: **HDBNC** 75Ω True 75™ High Density BNC Jacks & Plugs

HDBNC-BH1 – Jack, Right Angle Orientation, PCB Terminated



HDBNC-CA– Plug, Straight Orientation, Cable Terminated



Other configurations available for:

- Vertical cable-to-board applications
- Through-hole, edge mount
- Termination to various cable types

See www.samtec.com for more information.

Series: **HDBNC** 75Ω True 75™ High Density BNC Jacks & Plugs

1.0 SCOPE

1.1 This specification covers performance, testing and quality requirements for Samtec HDBNC Series. These connectors are available in through-hole and edge mount. All information contained in this specification is for a right angle jack through-hole connector to a straight plug cable connector unless otherwise noted.

2.0 DETAILED INFORMATION

2.1 Product prints, footprints, catalog pages, test reports and other specific, detailed information can be found at <http://www.samtec.com/rf/75-ohm/hdbnc.aspx>.

3.0 TESTING

3.1 Electrical:

ITEM	TEST CONDITION	REQUIREMENT	STATUS
Withstanding Voltage	EIA-364-20 (No Flashover, Sparkover, or Breakdown)	750 VAC	Pass
Insulation Resistance	EIA-364-21 (5000 MΩ minimum)	50,000 MΩ	Pass
Contact Resistance (LLCR)	EIA-364-23	Δ 15 mΩ maximum (Samtec defined)/ No damage	Pass

3.2 Mechanical:

ITEM	TEST CONDITION	REQUIREMENT	STATUS
Durability	EIA-364-09C	500 cycles (10μ" Au)	Pass
Random Vibration	EIA-364-28 Condition V, Letter B 7.56 G 'RMS', 50 to 2000 Hz, 2 hours per axis, 3 axis total, PSD 0.04	Visual Inspection: No Damage LLCR: Δ 15 mΩ maximum Event Detection: No interruption > 1.0 microsecond	Pass
Mechanical Shock	EIA-364-27 100 G, 6 milliseconds, sawtooth wave, 11.3 fps, 3 shocks/direction, 3 axis (18 total shocks)	Visual Inspection: No Damage LLCR: Δ 15 mΩ maximum Event Detection: No interruption > 50 Nanoseconds	Pass
Normal Force	EIA-364-04	30 grams minimum for gold interface	Pass



Series: **HDBNC** 75Ω True 75™ High Density BNC Jacks & Plugs

3.3 Environmental:

ITEM	TEST CONDITION	REQUIREMENT	STATUS
Thermal Shock	EIA-364-32 Thermal Cycles: 100 (30 minute dwell) Hot Temp: +85°C Cold Temp: -55°C Hot/Cold Transition: Immediate	Visual Inspection: No Damage LLCR: Δ 15 mΩ DWV: 390 VAC IR: >50,000 MΩ	Pass
Thermal Aging (Temp Life)	EIA-364-17 Test Condition 4 @ 105°C Condition B for 250 hours	Visual Inspection: No Damage LLCR: Δ 15 mΩ	Pass
Cyclic Humidity	EIA-364-31 Test Temp: +25°C to +65°C Relative Humidity: 90 to 95% Test Duration: 240 hours	Visual Inspection: No Damage LLCR: Δ 15 mΩ DWV: 390 VAC IR: >50,000 MΩ	Pass
Gas Tight	EIA-364-36 Gas Exposure: Nitric Acid Vapor Duration: 60 min. Drying Temp.: 50°C +/- 3°C Measurements: Within 1 hour of Exposure	LLCR: Δ 15 mΩ	Pass

Series: **HDBNC** 75Ω True 75™ High Density BNC Jacks & Plugs

4.0 MATED SYSTEM

4.1 Orientations



HDBNC-J-P-XX-ST-BHX TO
HDBNC-P-C-XX-ST-CAX



HDBNC-J-P-XX-RA-BHX TO
HDBNC-P-C-XX-ST-CAX

5.0 HIGH SPEED PERFORMANCE

5.1 Frequency Range:

Cable Type	CCA-1694A		CCA-1855A	
	RA	ST	RA	ST
Frequency Range	3G-SDI	3G-SDI	3G-SDI	3G-SDI

5.2 Impedance: 75 ohm

5.3 Rating: 3G-SDI

Series: **HDBNC** 75Ω True 75™ High Density BNC Jacks & Plugs

6.0 PROCESSING RECOMMENDATIONS

6.1 Due to variances in equipment, solder pastes and applications (board design, component density, etc.), Samtec does not specify a recommended reflow profile for our connectors. The processing parameters provided by the solder paste manufacturer should be employed and can usually be found on their website.

All of Samtec’s surface mount components are lead free reflow compatible and compliant with the profile parameters detailed in IPC/JEDEC J-STD-020E which requires that components be capable of withstanding a peak temperature of 260°C as well as 30 seconds above 255°C.

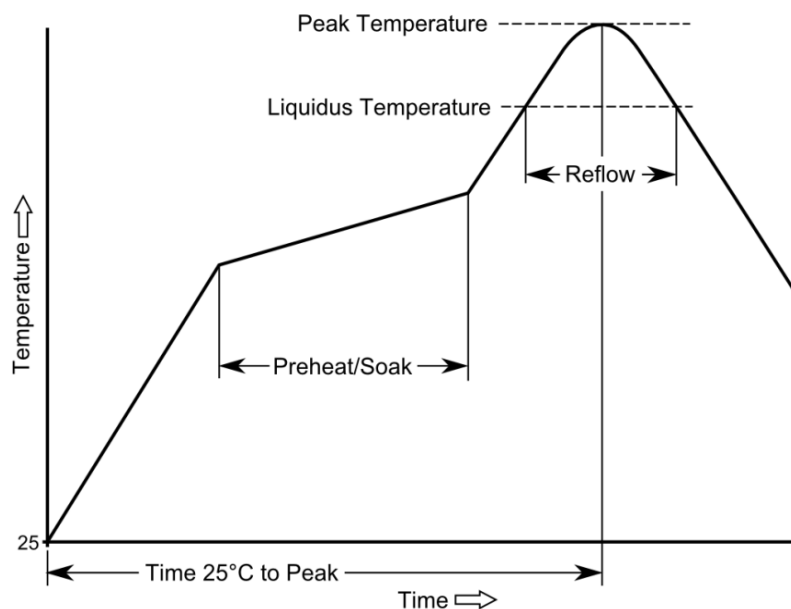
Samtec Recommended Temperature Profile Ranges (SMT)

Sn-Pb Eutectic Assembly

Preheat/Soak (100°C-150°C)	Max Ramp Up Rate	Reflow Time (above 183°C)	Peak Temp	Time within 5°C of 235°C	Max Ramp Down Rate	Time 25°C to Peak Temp
60-120 sec.	3°C/s max.	40-150 sec.	235°C	20 sec. max.	6°C/s max.	6 min. max.

Pb-Free Assembly

Preheat/Soak (150°C-200°C)	Max Ramp Up Rate	Reflow Time (above 217°C)	Peak Temp	Time within 5°C of 260°C	Max Ramp Down Rate	Time 25°C to Peak Temp
60-120 sec.	3°C/s max.	40-150 sec.	260°C	30 sec. max.	6°C/s max.	8 min. max.



6.1.1

These guidelines should not be considered design requirements for all applications. Samtec recommends testing interconnects on your boards in your process to guarantee optimum results.

Series: **HDBNC** 75Ω True 75™ High Density BNC Jacks & Plugs

6.2 Maximum Reflow Passes: The parts can withstand three reflow passes at a maximum component temperature of 260°C.

6.3 Stencil Thickness: The stencil thickness is .006" (0,15mm).

6.4 Placement: Machine placement of the parts is recommended.

6.5 Reflow Environment: Samtec recommends the use of a low level oxygen environment (typically achieved through Nitrogen gas infusion) in the reflow process to improve solderability.

6.6 Cleaning: Samtec, Inc. has verified that our connectors may be cleaned in accordance with the solvents and conditions designated in the EIA-364-11A standard.

7.0 APPLICATION INFORMATION

7.1 Min Cable Bend Radius: CCA-1694A = 2.750" [69.85mm]

7.2 Assembly Mating: Bayonet coupling mechanism

7.3 Cable Management: Samtec recommends some form of cable management to prevent non-axial forces being applied to the connector.

8.0 ADDITIONAL RESOURCES

8.1 For additional mechanical testing or product information, contact our Customer Engineering Support Group at CES@samtec.com

8.2 For additional information on high speed performance testing, contact our Signal Integrity Group at SIG@samtec.com

8.3 For additional processing information, contact our Interconnect Processing Group at IPG@samtec.com

8.4 For RoHS, REACH or other environmental compliance information, contact our Product Environmental Compliance Group at PEC@samtec.com

USE OF PRODUCT SPECIFICATION SHEET

This Product Specification Sheet ("PSS") is a brief summary of information related to the Product identified. As a summary, it should only be used for the limited purpose of considering the purchase/use of Product. For specific, detailed information, including but not limited to testing and Product footprint, refer to Section 2.0 of this document and the links there provided to test reports and prints. This PSS is the property of Samtec, Inc. ("Samtec") and contains proprietary information of Samtec, our various licensors, or both. Samtec does not grant express or implied rights or license under any patent, copyright, trademark or other proprietary rights and the use of the PSS for building, reverse engineering or replication is strictly prohibited. By using the PSS, the user agrees to not infringe, directly or indirectly, upon any intellectual property rights of Samtec and acknowledges that Samtec, our various licensors, or both own all intellectual property therein. The PSS is presented "AS IS". While Samtec makes every effort to present excellent information, the PSS is only provided as a guideline and does not, therefore, warrant it is without error or defect or that the PSS contains all necessary and/or relevant information about the Product. The user agrees that all access and use of the PSS is at its own risk. **NO WARRANTIES EXPRESSED OR IMPLIED, INCLUDING ANY WARRANTY OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR OF ANY KIND WHATSOEVER ARE PROVIDED**